

## PACKAGE STRUCTURE

### ABSTRACT OF THE DISCLOSURE

A package structure includes an insulation layer, a first conductive layer, a second conductive layer, at least one electronic component, and at least one thermal conduction structure. At least one first conductive via and at least one second conductive via are formed in the insulation layer. The first conductive layer is disposed on a top surface of the insulation layer and contacted with said at least one first conductive via. The second conductive layer is disposed on a bottom surface of the insulation layer and contacted with the second conductive via. The electronic component is embedded within the insulation layer, and includes plural conducting terminals. The plural conducting terminal is electrically connected with the first conductive layer and the second conductive layer through said at least one first conductive via and said at least one second conductive via. Said at least one thermal conduction structure is embedded within the insulation layer.

Fig. 1